

REMARKS

Applicant has amended independent claims 17 and 30 to include limitations regarding etch rate using hydrofluoric acid and regarding measurement of organic group content. Support for the amendments can be found on page 26, line 22 to page 27, line 7, and on page 28, lines 14-18 and at lines 22-24.

The phrase "an organic group content" is defined on page 26, line 22 to page 27, line 7, of the specification.

As amended, Applicant respectfully submits that these claims are patentable over the prior art for the following reasons:

In the coating film, an organic group is bonded to a silicon atom. The organic group decomposes at about 600°C when heated in an atmosphere wherein the oxygen concentration exceeds 1000 ppm. However, by heating the organic group in an atmosphere of reduced oxygen concentration, a film can be formed that suppresses the decomposition of the organic group even when baked at temperatures higher than 600°C. Surprisingly, by baking in a reduced oxygen concentration environment, the resistance to hydrofluoric acid on the resulting silica-based organic film is improved. Furthermore, degassing caused by increased temperatures can be suppressed even if the baking temperature is the same as in the case of baking in air. Consequently, it is possible to suppress phenomena such as film shrinkage due to vaporization of a gas, occurrence of cracking accompanying film shrinkage, and poor adhesion between the silica-based organic film and a film provided thereon.

The silica based organic film of the present invention contains at least certain amount of organic group and further, is dense due to high temperature baking, which brings excellent resistance to hydrofluoric acid to the present invention. Yamada and Kurosawa do not disclose at least the claimed etching rate and temperature. Therefore the present invention is not shown or suggested by Yamada and Kurosawa

CONCLUSION

Having addressed each and every ground of objection and rejection, applicants believe that the application is in condition for allowance. Applicants respectfully request reconsideration and allowance of the pending claims in the above-mentioned application and respectfully request that a timely Notice of Allowance be issued in this case.

Respectfully submitted,



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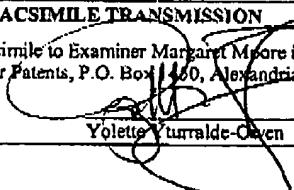
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CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being forwarded via facsimile to Examiner Margaret Moore in Group No. 1712 at facsimile number (703) 872.9306 located at Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA, 22313-1450, on

Date: October 13, 2005



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